

## An improved ASM-HEMT model for kink effect on GaN devices

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**Abstract:** With the analysis of experiment and theory on GaN HEMT devices under DC sweep, an improved model for kink effect based on advanced SPICE model for high electron mobility transistors (ASM-HEMT) is proposed, considering the relationship between the drain/gate-source voltage and kink effect. The improved model can not only accurately describe the trend of the drain-source current with the current collapse and kink effect, but also precisely fit different values of drain-source voltages at which the kink effect occurs under different gate-source voltages. Furthermore, it well characterizes the DC characteristics of GaN devices in the full operating range, with the fitting error less than 3%. To further verify the accuracy and convergence of the improved model, a load-pull system is built in ADS. The simulated result shows that although both the original ASM-HEMT and the improved model predict the output power for the maximum power matching of GaN devices well, the improved model predicts the power-added efficiency for the maximum efficiency matching more accurately, with 4% improved.

**Key words:** ASM-HEMT, DC, current collapse, kink effect

## GaN 器件 kink 效应建模研究

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**摘要:** 本文通过分析耗尽型 GaN 器件 kink 效应, 基于 ASM-HEMT 提出了一种改进模型。该模型考虑到漏源电压、栅源电压与 kink 效应的关系, 不仅能够准确模拟电流崩塌和 kink 效应发生时的漏源电流趋势, 而且精准拟合了不同栅源电压下 kink 效应发生时对应的漏源电压值  $V_{\text{dk}}$ , 表明改进模型能够准确表征 GaN 器件在整个工作电压范围内的直流特性, 拟合误差在 3% 以内。为了验证改进模型的精确度, 利用 ADS 负载牵引仿真电路进行了模型仿真, 仿真结果显示, 改进模型最佳效率匹配时的功率附加效率精确度比原始 ASM-HEMT 模型提高了 4%。

**关键词:** ASM-HEMT; 直流特性; 电流崩塌; kink 效应

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### Introduction

Gallium Nitride high electron mobility transistors (HEMTs) have promising prospects for high frequency,

high voltage and high power applications, due to their unique advantages of the material<sup>[1-2]</sup>. As the bridge between technological process and circuit design, models

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for GaN devices are critical. So far, behavioral models, empirical models and physical models have been reported<sup>[3-5]</sup>. Among these, ASM-HEMT (Advanced SPICE Model for HEMT), a physical surface-potential-based model, can accurately characterize the electrical characteristics of GaN devices with technological structure and physical mechanism well combined. Currently, ASM-HEMT has developed into the mainstream and been certified as the industry standardization<sup>[6]</sup>.

As an intrinsic reliability problem of GaN devices, kink effect features an abrupt rise in drain-source current  $I_{ds}$  after collapse at a certain drain-source voltage  $V_{ds}$ . The phenomenon deteriorates the stability of the device with a drop in the transconductance  $g_{m1}$ , an increase in the output conductance  $g_{ds1}$  as well as a shift in the threshold voltage  $V_{off}$ <sup>[7-9]</sup>. Because the kink effect on GaN devices cannot be completely eliminated, its influence in circuit design cannot be ignored. However, the current collapse and kink effect are not taken into consideration in the original ASM-HEMT. In order to more accurately characterize the performance of GaN devices, it is necessary to introduce the description of current collapse and kink effect to the model.

In this paper, an improved ASM-HEMT model for kink effect is proposed. This proposed model accurately describes the current collapse and kink effect, so as to precisely characterize the DC characteristics of GaN devices in the full operating range.

## 1 Theory of the improved model

### 1.1 The drain-source current $I_{ds}$ model in ASM-HEMT

By solving Schrodinger's and Poisson's equations, the potential of Fermi level corresponding to two-dimensional electron gas (2DEG) at GaN/AlGaIn hetero-junction can be calculated as<sup>[10]</sup>:

$$V_f = V_{go} - \frac{2V_{th} \ln \left( 1 + \exp \left( \frac{V_{go}}{2V_{th}} \right) \right)}{\frac{1}{H(V_{goeff})} + \frac{C_g}{qD} \exp \left( -\frac{V_{go}}{2V_{th}} \right)}, \quad (1)$$

$$V_{go} = V_{gs} - \left( V_{off} - \text{eta}0 \cdot \frac{vdscale \cdot V_{dsx}}{\sqrt{V_{dsx}^2 + vdscale^2}} \right), \quad (2)$$

where  $H(V_{goeff})$  is the function of  $V_{go}$ ,  $C_g$  is the gate capacitance per unit area,  $q$  is the electronic charge,  $D$  is the density of states,  $V_{th}$  is the thermal voltage,  $\text{eta}0$  and  $vdscale$  are the Drain Induced Barrier Lowering (DIBL) parameters,  $V_{off}$  is the threshold voltage, and  $V_{dsx} = \text{sqrt}(V_{ds}^2 + 0.01)$ .

So the potential at the source end  $\varphi_s$  and the potential at the drain end  $\varphi_d$  are obtained as follows<sup>[11]</sup>:

$$\varphi_s = V_f + V_s, \quad (3)$$

$$\varphi_d = V_f + V_{deff}, \quad (4)$$

where  $V_s$  is the source voltage, and  $V_{deff}$  is the effective drain voltage.

Combining the drift-diffusion mechanism with real device effects, the drain-source current  $I_{ds}$  is given as<sup>[12]</sup>:

$$I_{ds} = I_{ds}' \cdot (V_{go} - \varphi_m + V_{iv}) \cdot \varphi_{ds}, \quad (5)$$

$$I_{ds}' = \frac{W}{L} n_f C_g \mu_{eff} \frac{\left[ 1 + \lambda (V_{dsx} - V_{deff}) \right]}{\sqrt{1 + \theta_{sat}^2 \varphi_{ds}^2}}, \quad (6)$$

where  $W$  is the gate width,  $L$  is the gate length,  $n_f$  is the number of fingers,  $\mu_{eff}$  is the effective mobility,  $\theta_{sat}$  is the velocity saturation parameter,  $V_{iv}$  is the correction of  $V_{th}$ ,  $\varphi_m = (\varphi_s + \varphi_d)/2$ ,  $\varphi_{ds} = \varphi_d - \varphi_s$ , and  $\lambda$  is the channel length modulation coefficient.

### 1.2 The improved model for kink effect

The current collapse and kink effect can be obviously observed in the output characteristic curve of GaN devices, as shown in Fig. 1. At low  $V_{ds}$  ( $V_{ds} \approx 0-8$  V), electrons are trapped, leading to a decrease in channel carriers and a drop in the drain-source current, which is current collapse. As  $V_{ds}$  continues to increase, the trapped electrons are released, resulting in a rapid increase in the drain-source current, which features as the kink effect. The drain-source voltage where the kink effect occurs, defined as  $V_{ds-k}$ , is marked by the red triangle in Fig. 1. Meanwhile, when  $V_{gs}$  gradually increases,  $V_{ds-k}$  first drops and then increases. The above phenomenon demonstrates that both  $V_{ds}$  and  $V_{gs}$  play an important role in the current collapse and kink effect.

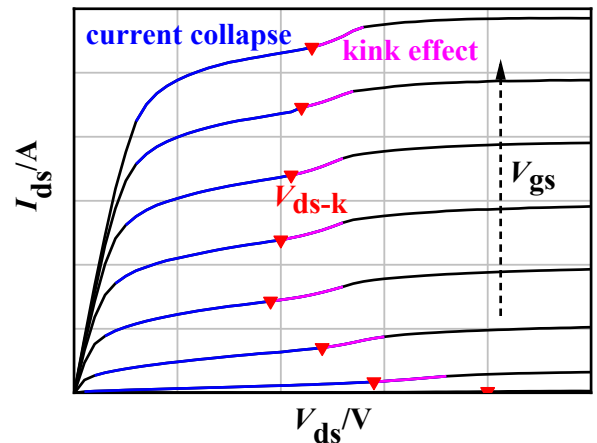


Fig. 1 Current collapse and kink effect in the output characteristics

图1 GaN HEMT 器件输出特性中的电流崩塌和kink效应

On account of the shift in the threshold voltage caused by the current collapse and kink effect,  $V_{off}$  in Eq. 2 needs to be corrected. By introducing the function  $CK(V_{ds}, V_{gs})$  related to  $V_{ds}$  and  $V_{gs}$ , the correction of the threshold voltage can be expressed as:

$$V_{off}' = \left[ 1 + CK(V_{ds}, V_{gs}) \right] \cdot V_{off}. \quad (7)$$

The tendency of  $I_{ds}$  rapidly increasing after collapse can be modeled by a hyperbolic tangent function  $\tanh$ <sup>[13]</sup>, which is exactly the form of  $CK(V_{ds}, V_{gs})$ :

$$CK(V_{ds}, V_{gs}) = d0 \cdot \tanh \left[ d1 \cdot (V_{ds} - V_{ds-k}) \right], \quad (8)$$

where  $d0$  and  $d1$  are fitting parameters, which determine the amplitude of current collapse and kink effect.

Considering the nonlinear relationship between  $V_{ds-k}$  and  $V_{gs}$ ,  $V_{ds-k}$  is given as a polynomial related to  $V_{gs}$ :

$$V_{ds-k} = g_0 + g_1 \cdot V_{gs} + g_2 \cdot V_{gs}^2 + g_3 \cdot V_{gs}^3 + \dots \quad (9)$$

where  $gk$  ( $k = 0, 1, 2, \dots$ ) is the fitting parameter.

Substituting Eq. 7 for  $V_{off}$  in Eq. 2, the final drain-source current  $I_{ds}$  can be rewritten as:

$$I_{ds} = I_{ds}' \cdot \left[ V_{gs} - \left( V_{off}' - \eta \cdot \frac{v_{dsc} \cdot V_{dsx}}{\sqrt{V_{dsx}^2 + v_{dsc}^2}} \right) - \varphi_m + V_{tv} \right] \cdot \varphi_{ds} \quad (10)$$

## 2 Modeling process

### 2.1 Devices and the test system

Two depletion-mode GaN HEMTs used in the paper are developed by Nanjing Electronic Devices Institute with gate widths of  $6 \times 200 \mu\text{m}$  and  $2 \times 200 \mu\text{m}$ , as shown in Fig. 2.

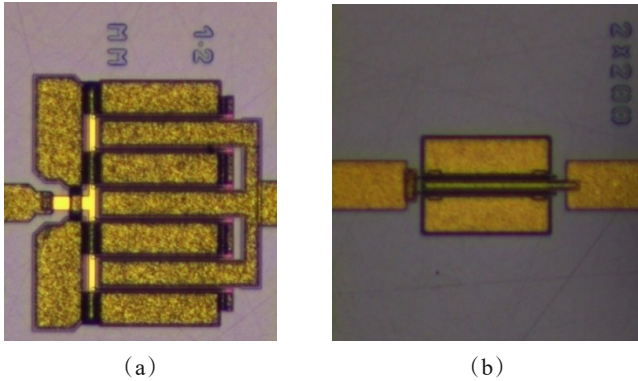


Fig. 2 Photographs of D-mode GaN HEMTs: (a) the 1.2-mm-wide device; (b) the 0.4-mm-wide device

图2 耗尽型 GaN HEMT 器件实物图: (a) 1.2 mm GaN 器件; (b) 0.4 mm GaN 器件

Firstly, as shown in Fig. 3, on-wafer measurement is carried out at room temperature ( $T = 300 \text{ K}$ ) for the DC characteristics, and the measured data is obtained through the IVCAD software of Maury Company. Secondly, the improved model is realized by Verilog-A and simulated on the ICCAP software. Finally, based on the measurements, parameters of the improved model are extracted and the DC characteristics are fitted, including the output characteristics  $I_{ds}-V_{ds}$ , the output conductance (the first derivative of  $I_{ds}$  with respect to  $V_{ds}$ )  $g_{ds1}-V_{ds}$ , the transfer characteristics  $I_{ds}-V_{gs}$  and the transconductance (the first derivative of  $I_{ds}$  with respect to  $V_{gs}$ )  $g_{m1}-V_{gs}$ , measured and simulated with the value of  $V_{ds}$  varying from 0 V to 36 V in the step of 0.2 V and the value of  $V_{gs}$  changing from -4 V to 0 V in the step of 0.1 V.

### 2.2 Parameters extraction

For the output characteristics and the S-parameter, the fitting results of the original ASM-HEMT and the im-

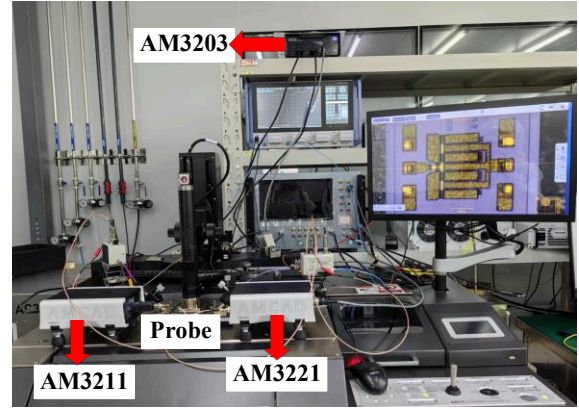
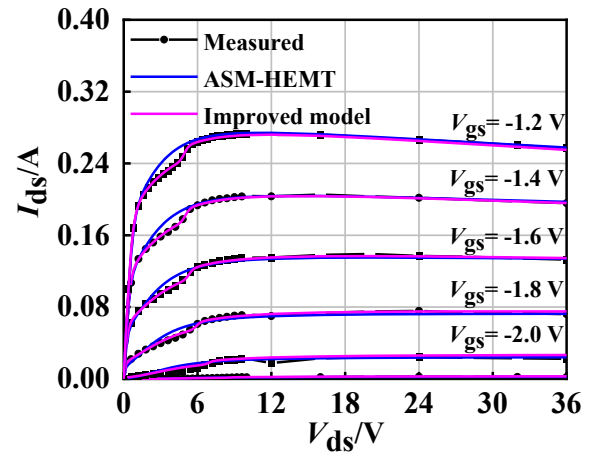
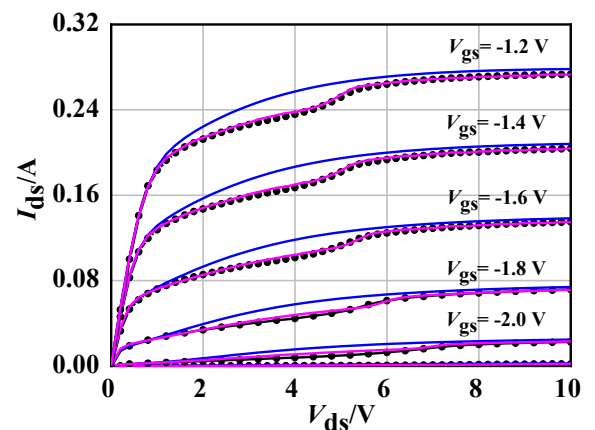


Fig. 3 The test system  
图3 测试平台

proved model are shown in Figs. 4-6.



(a)



(b)

Fig. 4 The fitting result of the output characteristics  $I_{ds}-V_{ds}$  for the 1.2-mm-wide device: (a)  $V_{ds}$  ranges from 0 V to 36 V; (b)  $V_{ds}$  ranges from 0 V to 10 V

图4 1.2 mm GaN 器件输出特性  $I_{ds}-V_{ds}$  拟合结果: (a)  $V_{ds}=0\sim 36 \text{ V}$ ; (b)  $V_{ds}=0\sim 10 \text{ V}$

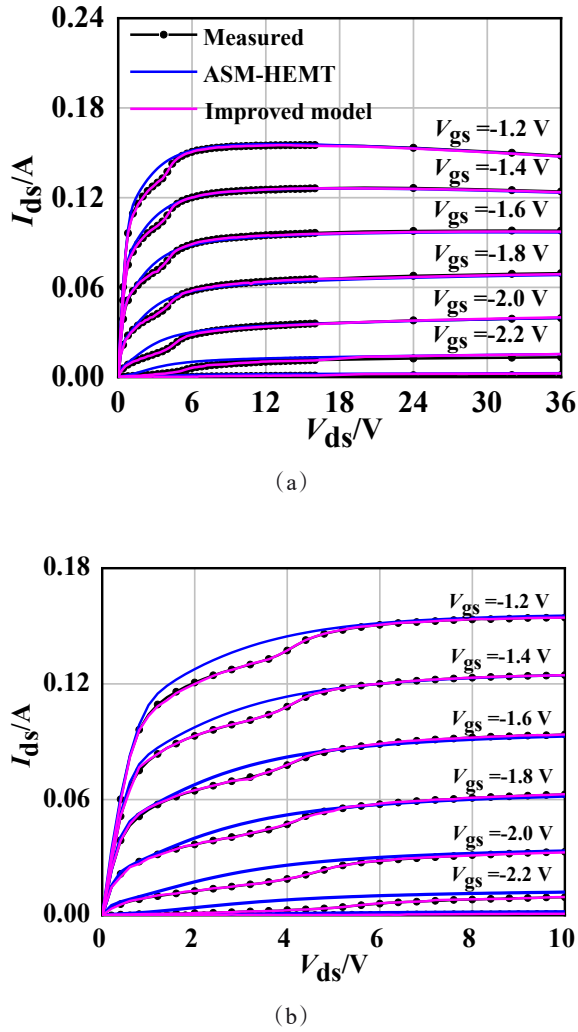


Fig. 5 The fitting result of the output characteristics  $I_{ds}$ - $V_{ds}$  for the 0.4-mm-wide device: (a)  $V_{ds}$  ranges from 0 V to 36 V; (b)  $V_{ds}$  ranges from 0 V to 10 V

图5 0.4 mm GaN 器件输出特性  $I_{ds}$ - $V_{ds}$  拟合结果: (a)  $V_{ds}=0\sim 36$  V; (b)  $V_{ds}=0\sim 10$  V

### 2. 2. 1 Fitting of the output characteristics curves

Seen from Fig. 4(a) and Fig. 5(a), both the original ASM-HEMT and the improved model fits to the measured curve well in the saturation region, but there are obvious differences in the regions where the current collapse and kink effect occur. The accuracy of the original ASM-HEMT is insufficient, as shown in Fig. 4(b) and Fig. 5(b). For the improved model,  $I_{ds}$  behaves an abrupt rise after collapse as  $V_{ds}$  increases, and  $V_{ds-k}$  under different  $V_{gs}$  is also perfect fitted.

### 2. 2. 2 Fitting of the S-parameter

The S-parameter simulation results from 400 MHz to 40 GHz of the original model and the improved model are

compared with the measurements for two devices, as shown in Fig. 6.

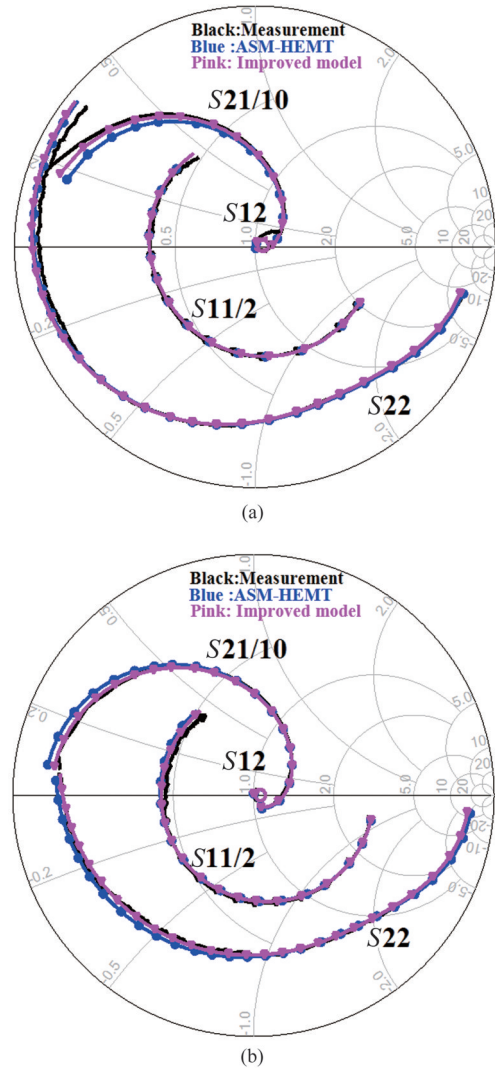


Fig. 6 The fitting result of the S-parameter: (a) the 1.2-mm-wide device; (b) the 0.4-mm-wide device

图6 S参数拟合结果: (a) 1.2 mm GaN 器件; (b) 0.4 mm GaN 器件

For the small signal characteristic at  $V_{gs} = -2.2$  V and  $V_{ds} = 28$  V, the good agreement between the measured results and both of the simulated results is obtained. Because the input is the small signal, the impact of kink effect on the RF characteristics can be ignored.

### 2. 2. 3 Final parameters

Finally, the extracted parameters are obtained in Table 1 and Table 2.

The above results indicate that the improved model can accurately describe the current collapse and kink ef-

Table 1 The extracted parameters related to the current collapse and kink effect for the 1.2-mm-wide device

表1 1.2 mm GaN 器件电流崩塌和 kink 效应相关参数值

The fitting parameter	$d0$	$d1$	$g0$	$g1$	$g2$	$g3$	$g4$
Value	5.234 m	10	2.506	18.15 m	69.02 m	218.3 m	151.4 m

**Table 2** The extracted parameters related to the current collapse and kink effect for the 0.4-mm-wide device  
**表 2** 0.4 mm GaN 器件电流崩塌和 kink 效应相关参数值

The fitting parameter	$d0$	$d1$	$g0$	$g1$	$g2$	$g3$	$g4$
Value	21.83 m	3.793	3.282	477.5 m	584.2 m	0.001 m	3.451 m

fect, and characterize the output characteristics of GaN devices with different sizes.

### 3 Results

The fitting result of the output conductance ( $V_{gs} = -1.2$  V for the 1.2-mm-wide device in this paper) is shown in Fig. 7. It can be seen that the improved model appears a peak near  $V_{ds} = 4$  V, which agrees with the description in Ref. [14] and is well matched with the measured data, further proving that the improved model accurately describes the current collapse and kink effect of GaN devices.

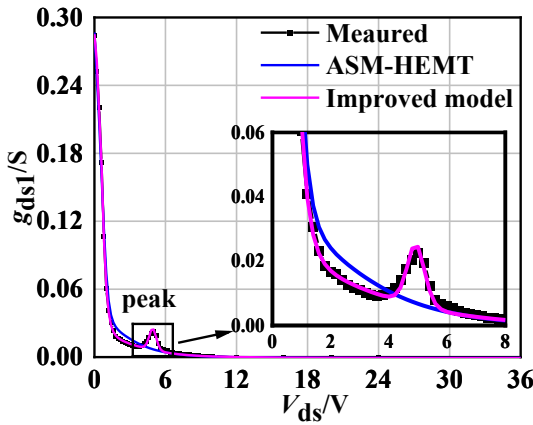


Fig. 7 The fitting result of the output conductance  $g_{ds1}-V_{ds}$   
 图 7 输出电导  $g_{ds1}-V_{ds}$  拟合结果

Figure 8 shows the fitting results of the transfer characteristics at  $V_{ds} = 4$  V and  $V_{ds} = 28$  V. The original ASM-HEMT fits well where  $V_{ds}$  is high ( $V_{ds} = 28$  V for the 1.2-mm-wide device in this paper), but the fitting error is large where  $V_{ds}$  is low ( $V_{ds} = 4$  V for the 1.2-mm-wide device in this paper), while the improved model can achieve an excellent fit under all  $V_{ds}$ . Accordingly, the transconductance of the improved model agrees well with the measured data, as shown in Fig. 9, indicating that the improved model accurately characterizes the transfer characteristics of GaN devices by introducing parameters related to the current collapse and kink effect.

According to the above results, the improved model perfectly fits the kink effect of GaN devices. Clearly, the improved model accurately describes the current collapse and kink effect, so as to precisely characterize the DC characteristics of GaN devices in the full operating range.

To further verify the accuracy of the improved model, a load-pull simulation is built in ADS, as shown in Fig. 10. The improved model is validated by simulating the large signal behavior at 3 GHz and  $I_{dsq} = 12$  mA at  $V_{ds} = 28$  V, with the input power  $P_{in}$  swept from 1 dBm to 24 dBm.

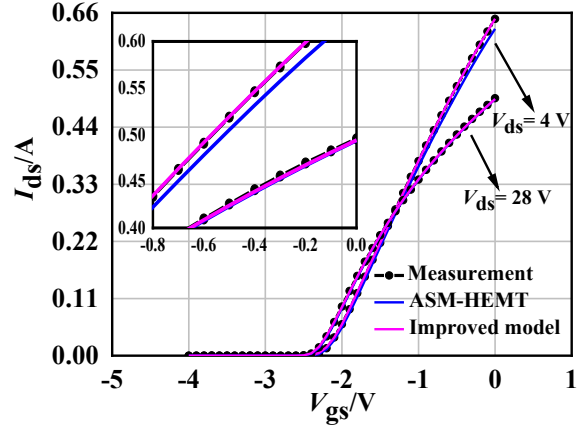


Fig. 8 The fitting result of the transfer characteristics  $I_{ds}-V_{gs}$   
 图 8 转移特性  $I_{ds}-V_{gs}$  拟合结果

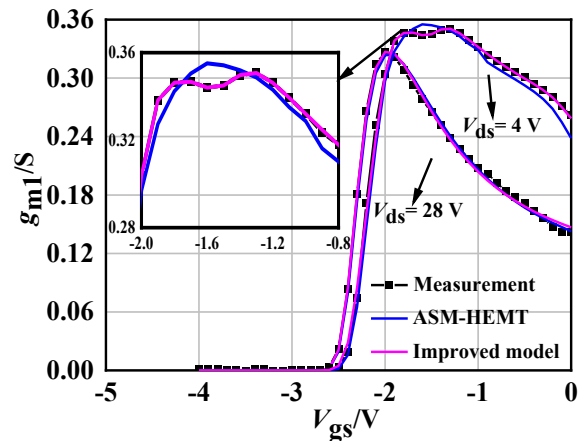


Fig. 9 The fitting result of the transconductance  $g_{m1}-V_{gs}$   
 图 9 跨导  $g_{m1}-V_{gs}$  拟合结果

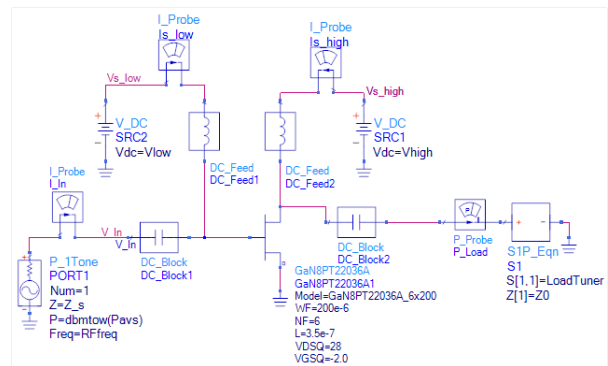


Fig. 10 Schematic diagram of the load-pull simulation in ADS  
 图 10 ADS 负载牵引仿真原理图

As shown in Fig. 11, both the original ASM-HEMT and the improved model can predict the output power for the maximum power matching of GaN devices well. How-

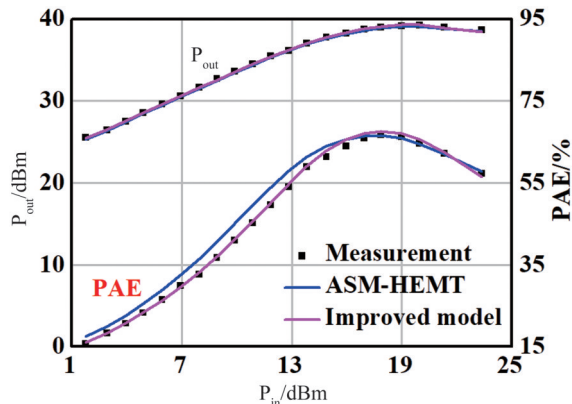


Fig. 11 Simulated and measured  $P_{out}$  for the maximum power matching and PAE for the maximum efficiency matching  
图 11 最佳功率匹配时输出功率  $P_{out}$ 、最佳效率匹配时功率附加效率 PAE 的仿真结果和测试结果

ever, compared with the original ASM-HEMT, the improved model predicts the power-added efficiency (PAE) for the maximum efficiency matching more accurately, with 4% improved, which has a good agreement with the measured result.

## 4 Conclusions

An improved model for kink effect based on ASM-HEMT is presented in this paper, considering the impact of  $V_{ds}$  and  $V_{gs}$ . Validated with the experimental data, the improved model can accurately describe the current collapse and kink effect, and more accurately characterize the DC characteristics of GaN devices in the full range of voltage, with the fitting error less than 3%. Compared with the original ASM-HEMT, the improved model predicts the power-added efficiency for the maximum efficiency matching more accurately without changing the accuracy of the output power for the maximum power matching. The improved model is of great guiding significance for the accurate design of high-performance GaN amplifiers, and can also play a crucial role in reducing circuit design costs and shortening the product development cycle. Since GaN devices used in the paper adopt a process of  $0.35 \mu\text{m}$ , they are not suitable for millimeter waves. To further broaden the applicability of the improved model, GaN devices for higher frequency will be studied in

the future.

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